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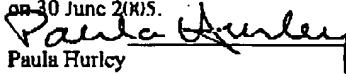
No. 0287 P. 1

JUN 30 2005

Attorney Docket No.: CPAC 1029-5

**CERTIFICATE OF TRANSMISSION UNDER 37 CFR 1.8**

I hereby certify that this correspondence is being facsimile transmitted  
to the United States Patent and Trademark Office at Fax No. (703) 872-9306  
on 30 June 2005.

  
Paula Hurley

30 June 2005

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of:

Marcos Karnezos

Application No. 10/681,583

Confirmation No.: 6814

Filed: 08 October 2003

Title: Semiconductor Multi-Package Module  
Having Inverted Second Package Stacked Over  
Die-down Flip-chip Ball Grid Array (BGA)  
Package

Group Art Unit: 2841

Examiner: Unassigned

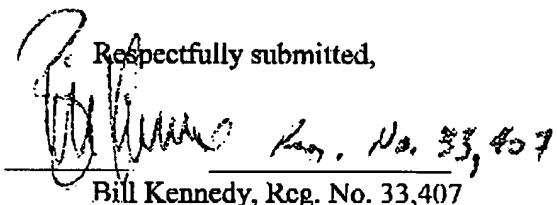
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Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**SECOND STATUS INQUIRY**

Sir:

The last correspondence received from the Patent Office for the subject application is a Filing  
Receipt mailed 09 March 2004. Please inform the undersigned when this application will be examined.

  
Respectfully submitted,  
Bill Kennedy, Reg. No. 33,407

Dated: 30 June 2005

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